Docket No.

245102US2SX DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

Hiroyuki KANAYA, et al.

SERIAL NO:

10/706,970

GAU:

2818

November 14, 2003

EXAMINER: TRAN, LONG K.

FOR: SFP 0 1 2004

SEMICONDUCTOR DEVICE HAVING FERROELECTRIC FILM AND MANUFACTURING METHOD THEREOF

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

SIONER FOR PATENTS LEXANDRIA, VIRGINIA 22313

Applicant(s) wish to disclose the following information.

REFERENCES

The applicant(s) wish to make of record the references cited in the attached Japanese Office Action with English Translation and listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.

A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. In accordance with discussions on August 4, 2004 with Mr. Nicholas P. Godici, Commissioner for Patents, it is no longer required to submit copies of cited pending applications. A modification of the Rules will be published soon in the Official Gazette. Cited issued patents, if any, are listed on the attached PTO form 1449.

☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.

No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBŁON, SPIVAK, McCLELLAND,

MAIER/& NEUSTADT. P.C

Eckhard H. Kuesters

Registration No. 28,870

Customer Number

Tel. (703) 413-3000 Fax. (703) 413-2220 (OSMMN 05/03) EHK/JW/agm I:\ATTY\JW\245102US2XDIV\245102US IDS TL.DOC

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		PATENT AND TRADEMARK OFFICE		245102US2SX DIV		10/706,970	
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LIST OF REFERENCES CITED BY APPLICANT Hiroyuki KANAYA, et al.							
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FOREIGN PATENT DOCUMENTS							
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OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
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Examiner					Date Considered		
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							
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